



# HTIP112

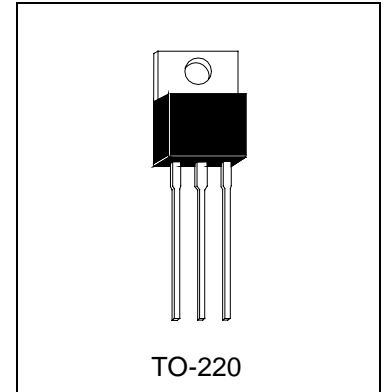
NPN EPITAXIAL PLANAR TRANSISTOR

## Description

The HTIP112 is designed for use in general purpose amplifier and low-speed switching applications.

## Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
  - Storage Temperature ..... -55 ~ +150 °C
  - Junction Temperature ..... +150 °C Maximum
- Maximum Power Dissipation
  - Total Power Dissipation (Tc=25°C) ..... 50 W
  - Total Power Dissipation (Ta=25°C) ..... 2 W
- Maximum Voltages and Currents
  - BVCBO Collector to Base Voltage ..... 100 V
  - BVCEO Collector to Emitter Voltage ..... 100 V
  - BVEBO Emitter to Base Voltage ..... 5 V
  - IC Collector Current (Continue) ..... 4 A
  - IC Collector Current (Peak) ..... 6 A

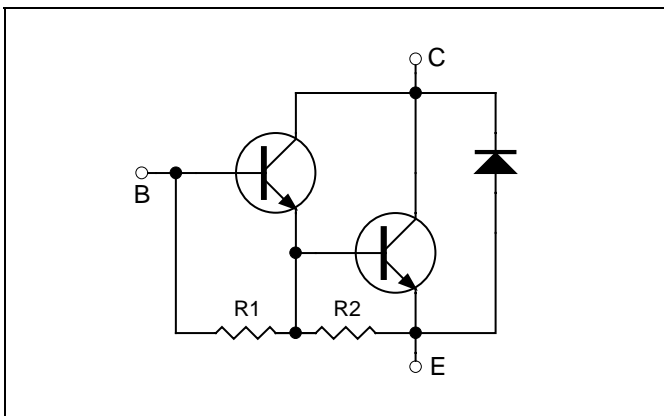


## Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	100	-	-	V	IC=1mA
BVCEO	100	-	-	V	IC=30mA
ICBO	-	-	1	mA	VCB=100V
ICEO	-	-	2	mA	VCE=50V
IEBO	-	-	2	mA	VEB=5V
*VCE(sat)	-	-	2.5	V	IC=2A, IB=8mA
*VBE(on)	-	-	2.8	V	IC=2A, VCE=4V
*hFE1	1	-	-	K	IC=1A, VCE=4V
*hFE2	500	-	-		IC=2A, VCE=4V
Cob	-	-	200	pF	VCB=10V, f=0.1MHz

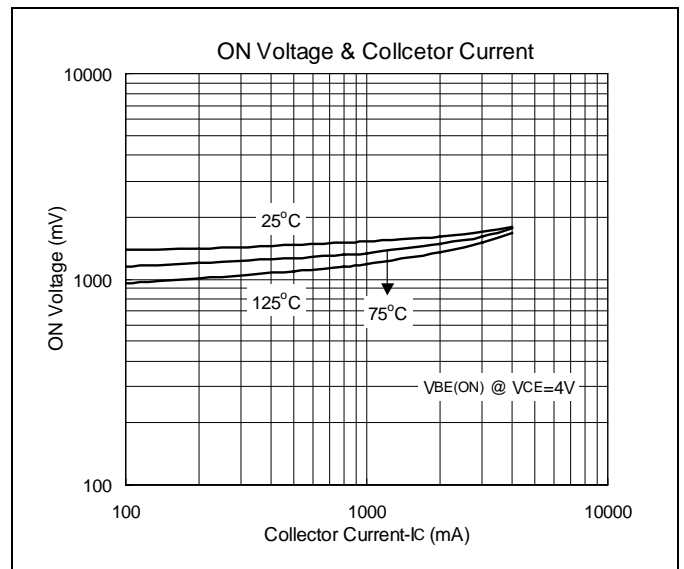
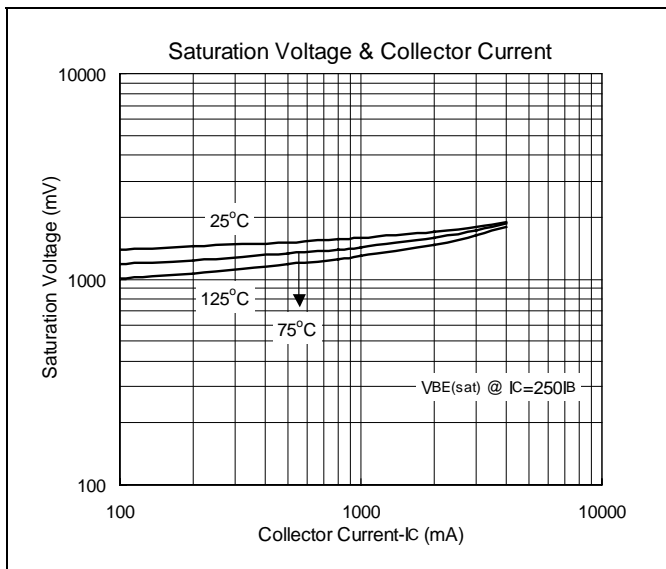
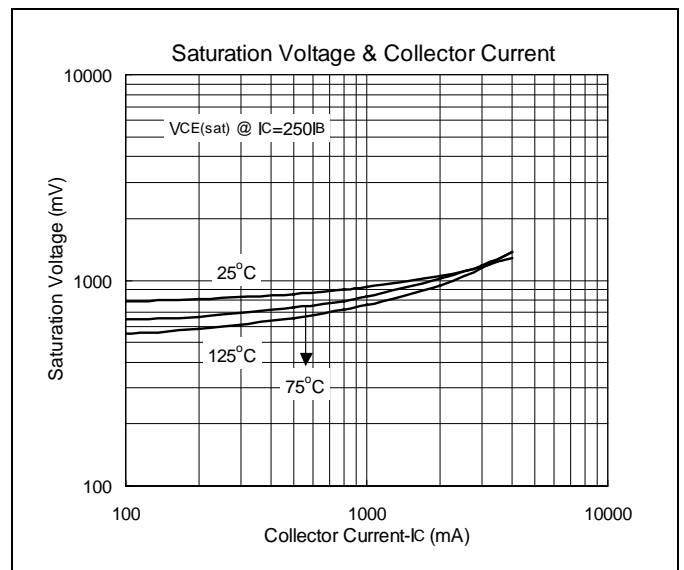
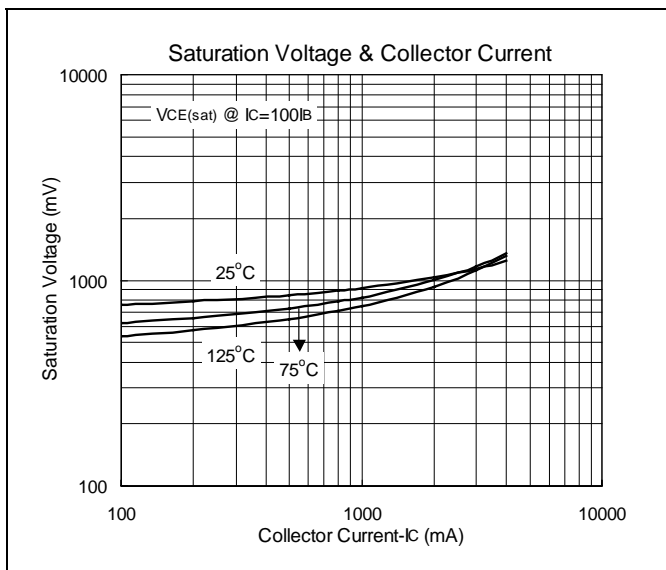
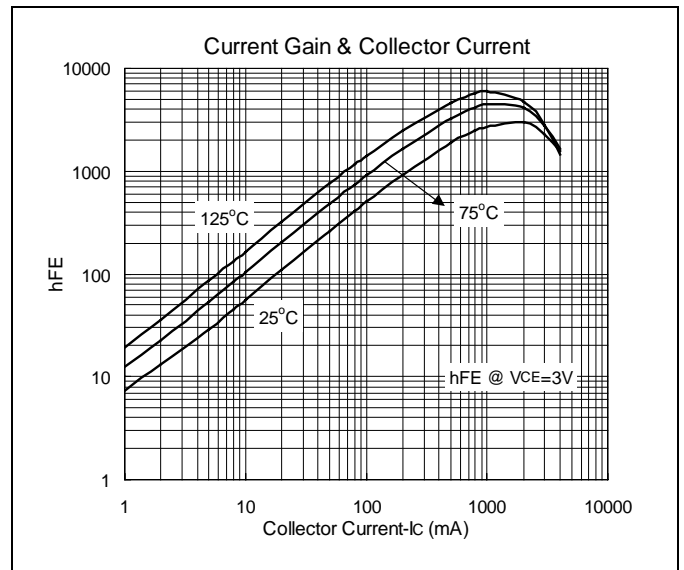
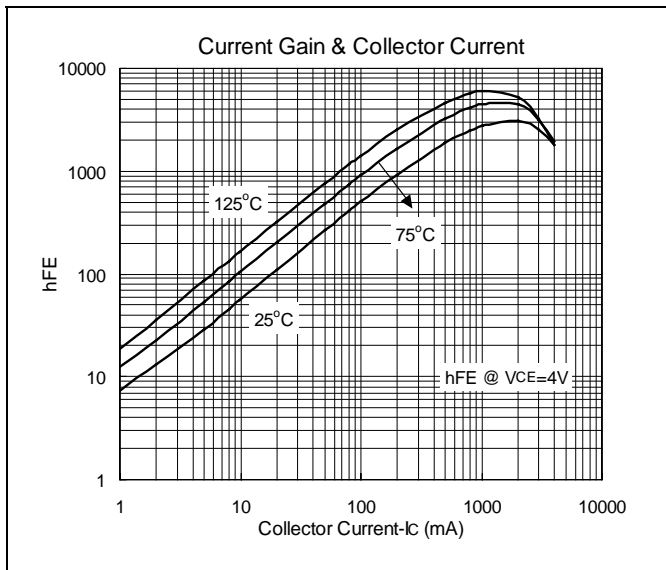
\*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%

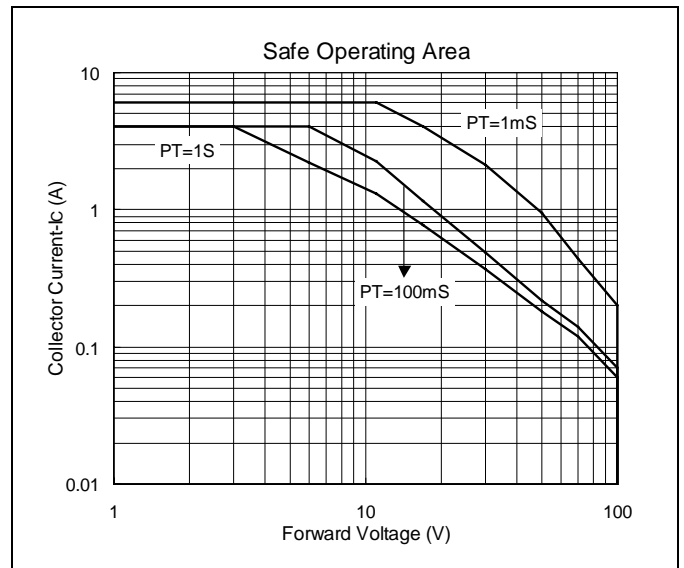
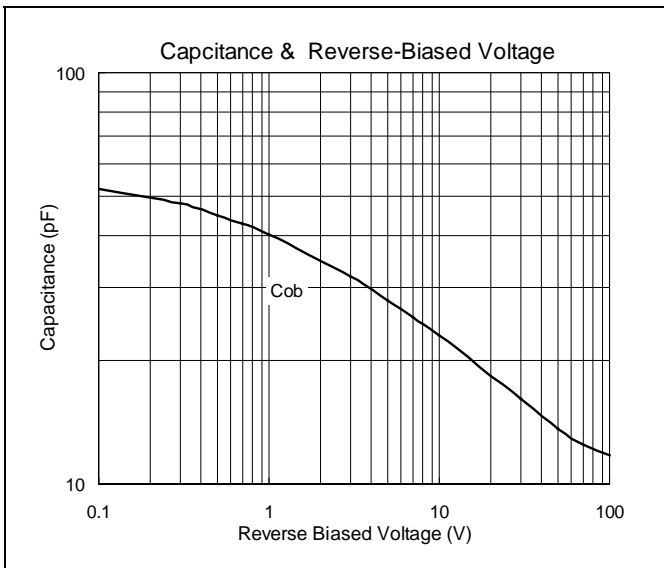
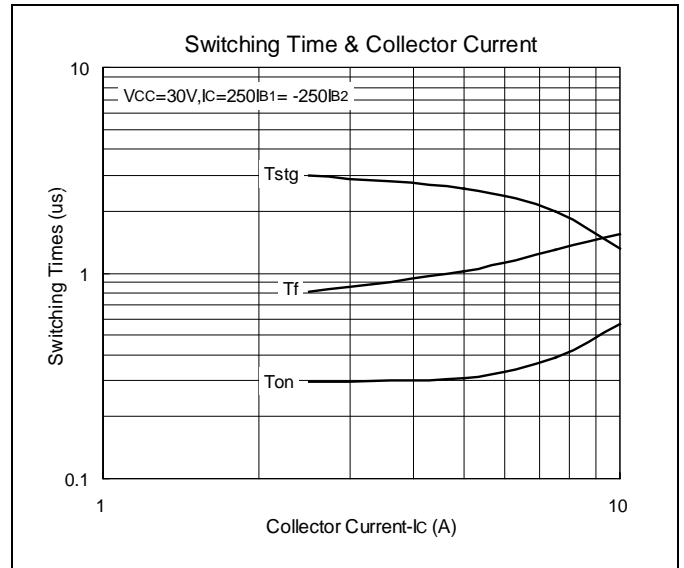
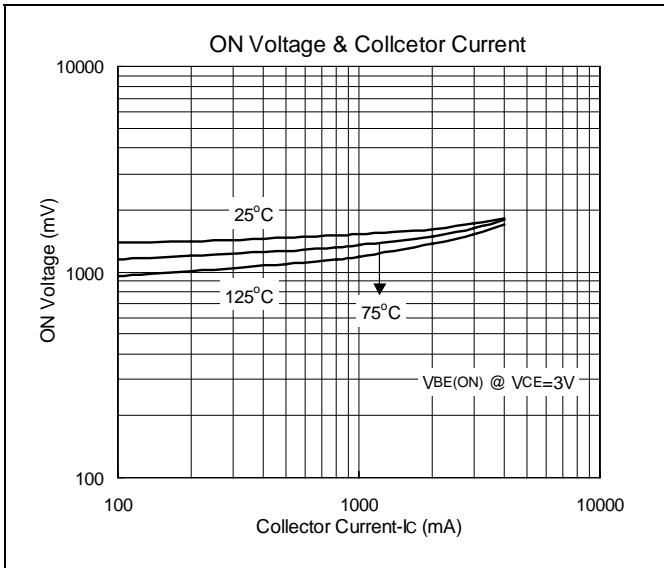
## Darlington Schematic





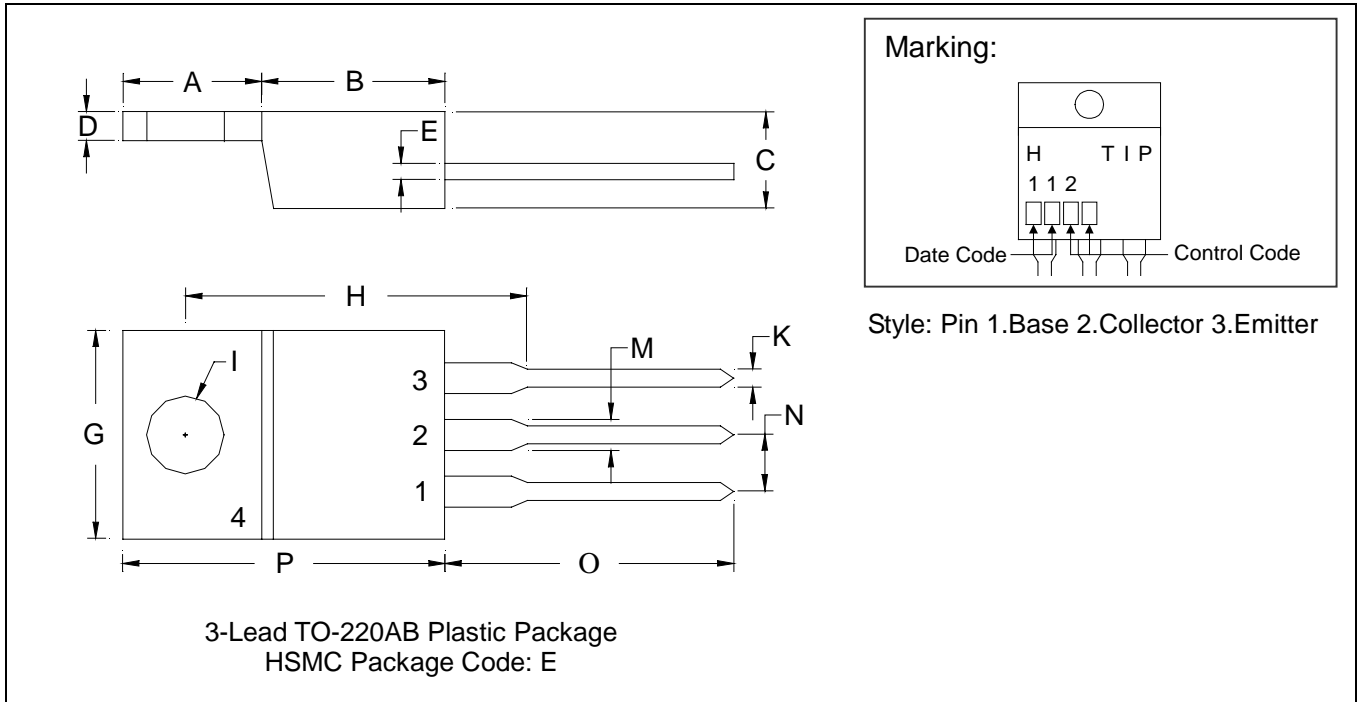
### Characteristics Curve







### TO-220AB Dimension



\*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.2197	0.2949	5.58	7.49	I	-	*0.1508	-	*3.83
B	0.3299	0.3504	8.38	8.90	K	0.0295	0.0374	0.75	0.95
C	0.1732	0.185	4.40	4.70	M	0.0449	0.0551	1.14	1.40
D	0.0453	0.0547	1.15	1.39	N	-	*0.1000	-	*2.54
E	0.0138	0.0236	0.35	0.60	O	0.5000	0.5618	12.70	14.27
G	0.3803	0.4047	9.66	10.28	P	0.5701	0.6248	14.48	15.87
H	-	*0.6398	-	*16.25					

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated Sep. 07,1997.
  - 2.Controlling dimension: millimeters.
  - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
  - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

**Material:**

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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**Head Office And Factory:**

- **Head Office** (Hi-Sincerity Microelectronics Corp.): 10F.,No. 61, Sec. 2, Chung-Shan N. Rd. Taipei Taiwan R.O.C.  
Tel: 886-2-25212056 Fax: 886-2-25632712, 25368454
- **Factory 1:** No. 38, Kuang Fu S. Rd., Fu-Kou Hsin-Chu Industrial Park Hsin-Chu Taiwan. R.O.C  
Tel: 886-3-5983621~5 Fax: 886-3-5982931